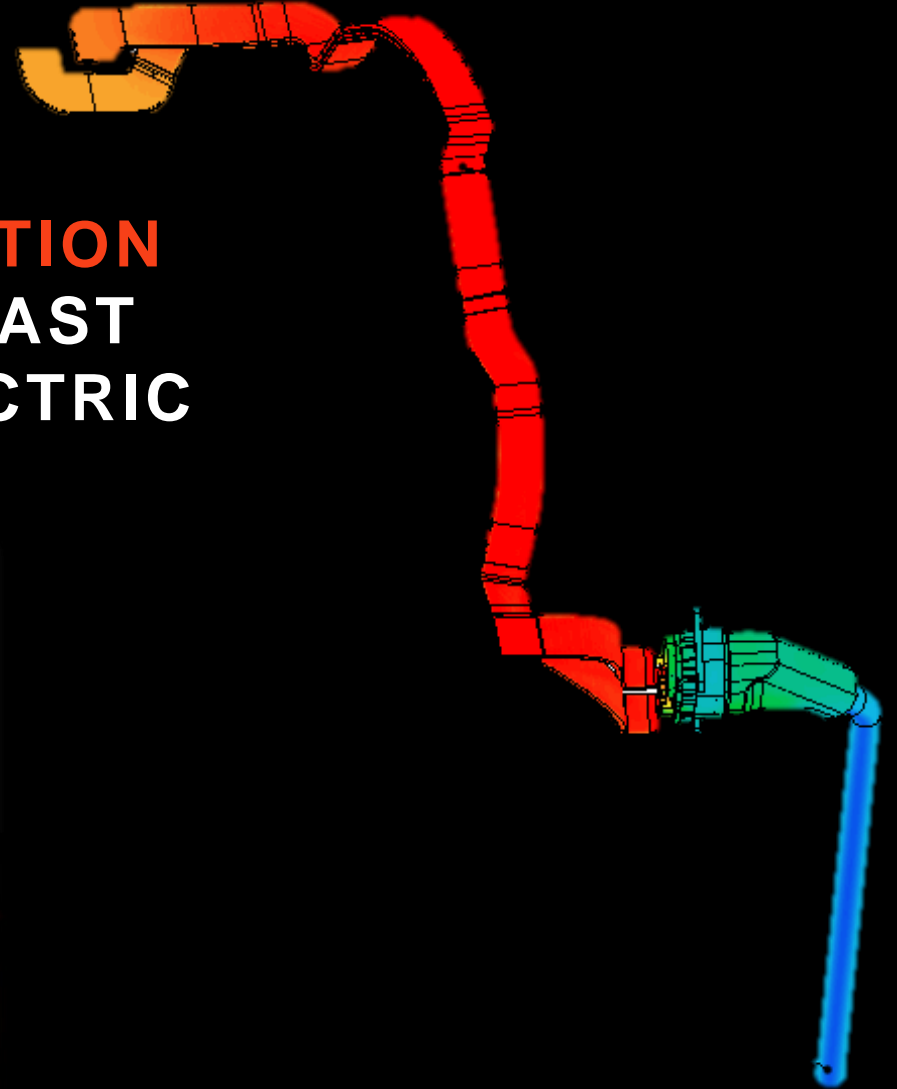


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*Thermal Management Expo*

**Monika Pieszka**  
Senior Simulation Expert

# CFD AND THERMAL-ELECTRIC SIMULATION METHODOLOGY FOR HIGH-CURRENT FAST CHARGING INFRASTRUCTURE OF ELECTRIC VEHICLES



• **APTIV** •

The collage displays a variety of engineering simulation results:

- Top Left:** A 3D model of a mechanical component with a color-coded stress or temperature distribution.
- Top Center-Left:** A FLIR thermal image showing a heat map of a component with a temperature scale from 23.9 to 54.1 °C.
- Top Center-Right:** A line graph showing a peak in a variable (likely temperature or stress) over time or distance, with a color-coded legend.
- Top Right:** A 3D model of a component with a green line indicating a specific path or trajectory.
- Middle Left:** A graph showing the relationship between a variable (likely temperature or stress) and a parameter (likely time or distance), with a color-coded legend.
- Middle Center-Left:** A 3D model of a component with a color-coded stress or temperature distribution.
- Middle Center-Right:** A 3D model of a component with a color-coded stress or temperature distribution, labeled "NTSL".
- Middle Right:** A 3D model of a component with a color-coded stress or temperature distribution, labeled "Stage 1 Stage 1 Frames 14".
- Bottom Left:** A 3D model of a component with a color-coded stress or temperature distribution, labeled "Fig. 7".
- Bottom Center-Left:** A FLIR thermal image showing a heat map of a component with a temperature scale from 20.6 to 22.0 °C.
- Bottom Center-Right:** A 3D model of a component with a color-coded stress or temperature distribution.
- Bottom Right:** A 3D model of a component with a color-coded stress or temperature distribution, labeled "Time: 400s".

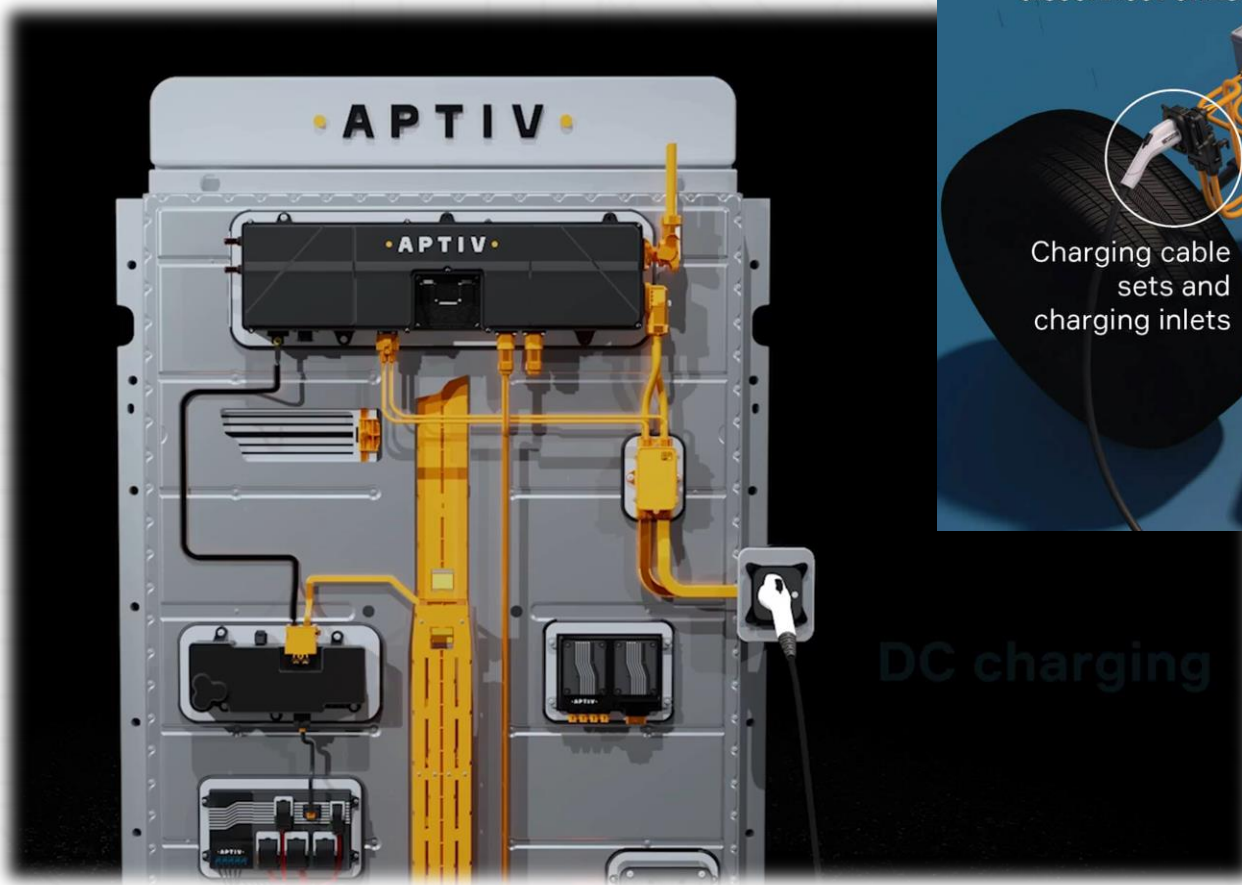
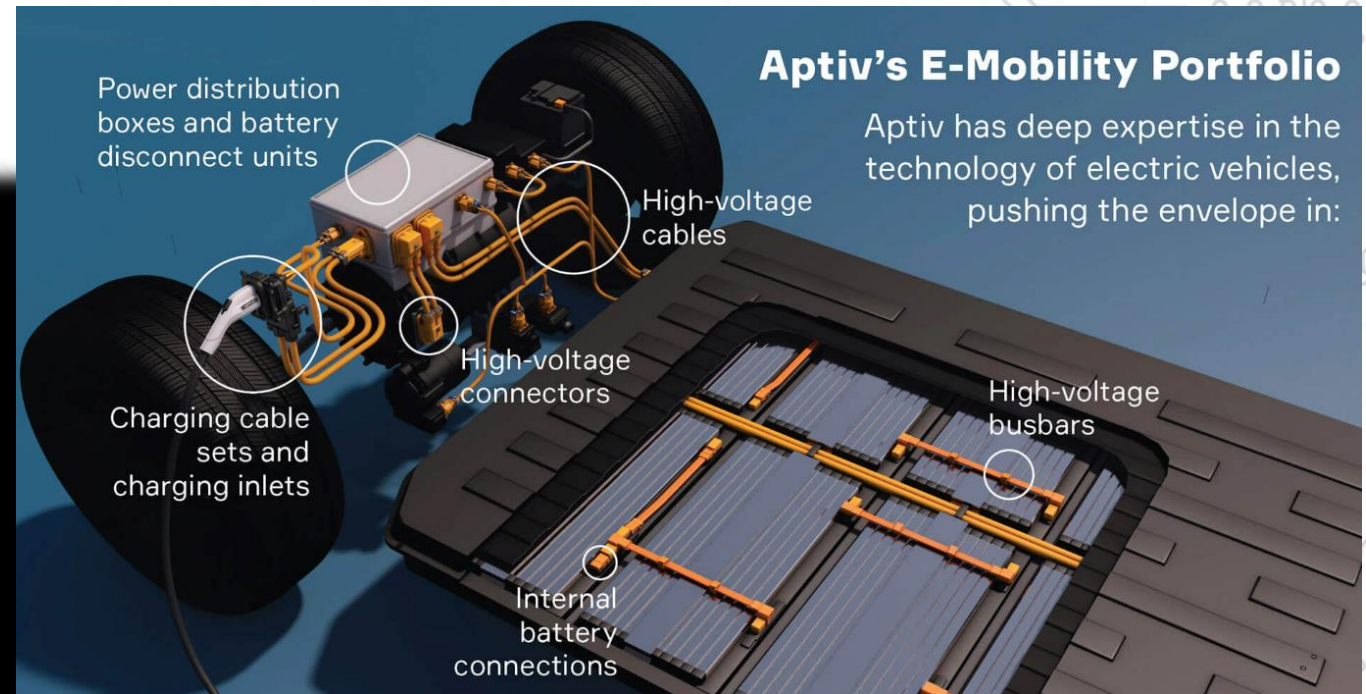


**& PhD Candidate, AGH University of Krakow**

- **Simcenter FlothermXT** • **Simcenter FloEFD** • **Ansys Fluent** • **Abaqus/CAE** • **Simcenter StarCCM+**

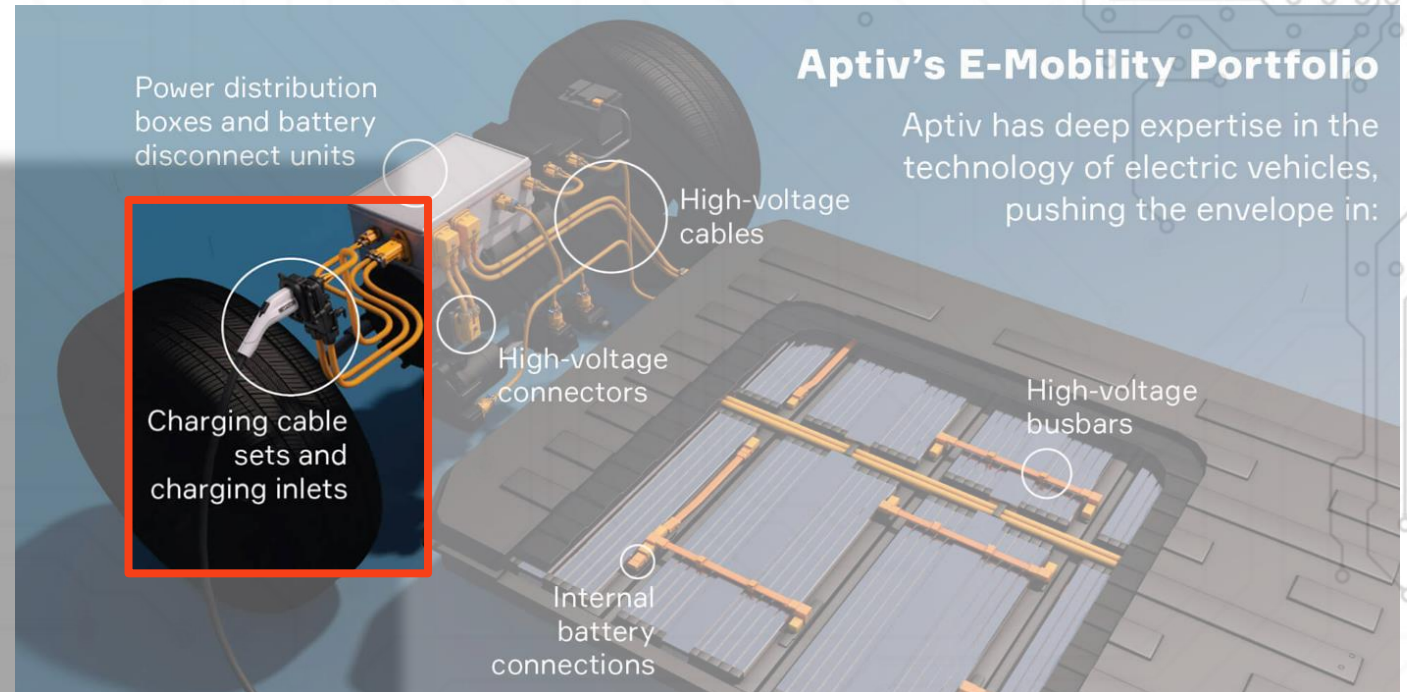
- **M. Pieszka-Łysoń, P. Růtkowski, M. Kawalec, D. Kawalec. 2024. "Determination of Contact Resistance of Thermal Interface Materials Used in Thermal Monitoring Systems of Electric Vehicle Charging Inlets" *Materials* 17, no. 13: 3103. <https://doi.org/10.3390/ma17133103>**
- **Patents: <https://www.linkedin.com/in/monikapieszka/details/patents/>**

# Aptiv Signal and Power Solutions Portfolio





# Focus on Charging Infrastructure



- Charging Inlets for OEMs
- Very big influence of a Charging Station
- High-voltage Harness (Cables, Busbars)
- Modelling based on IEC standard
- Calibrations based on Internal Thermal Tests

# Simulation methodology

**CFD  
simulations  
(thermal,  
electric,  
flow)**

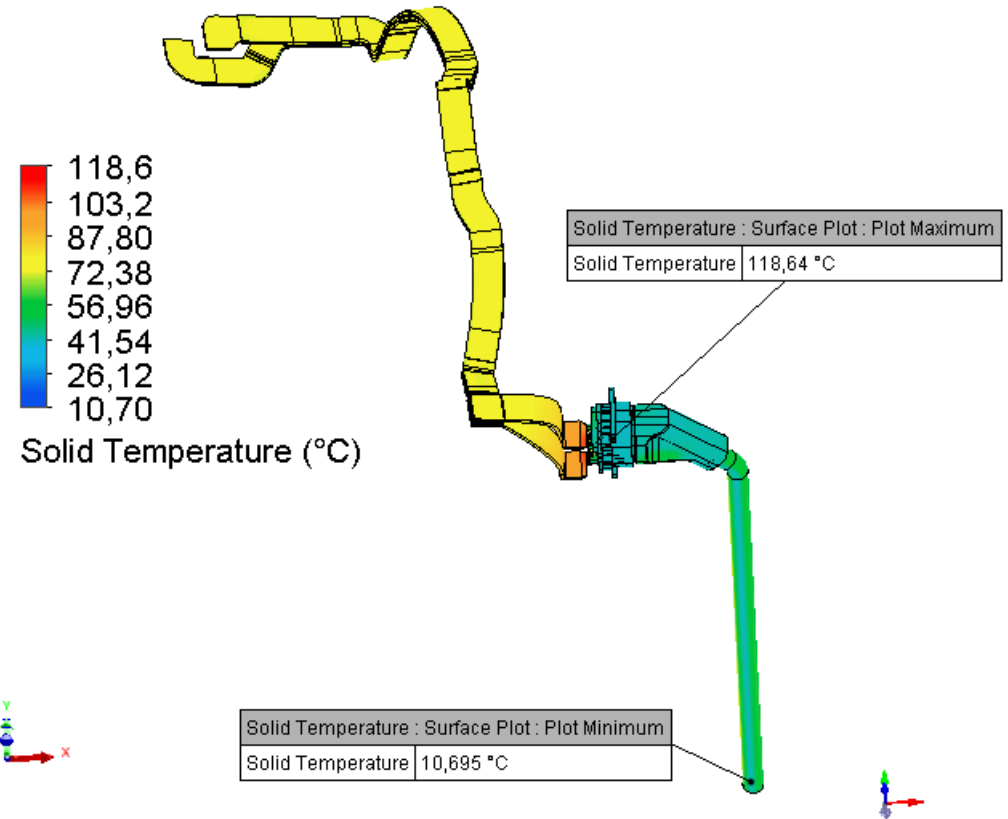
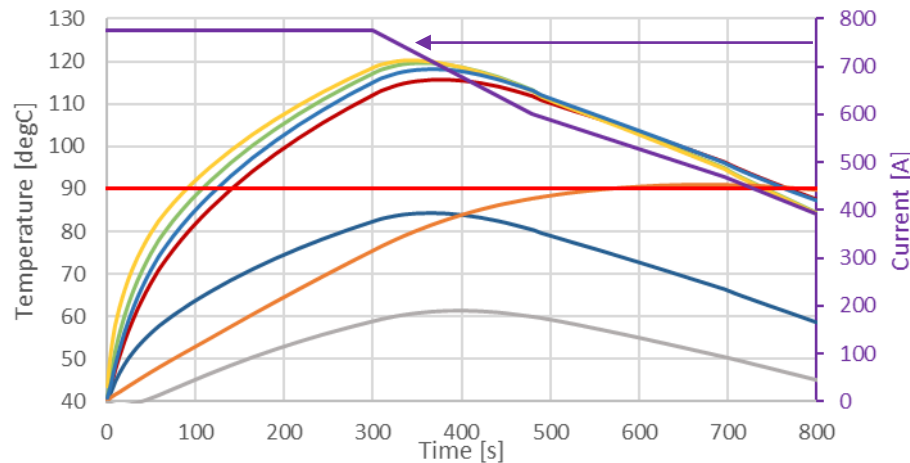
**FEM  
simulations  
(thermal,  
electric)**

**Other high-  
fidelity CFD  
simulations  
(multiphase,  
multiphysics)**

**Reduced  
Order Models  
(0-1D, RC  
models,  
AI/ML  
models)**

# CFD thermal-electric simulation

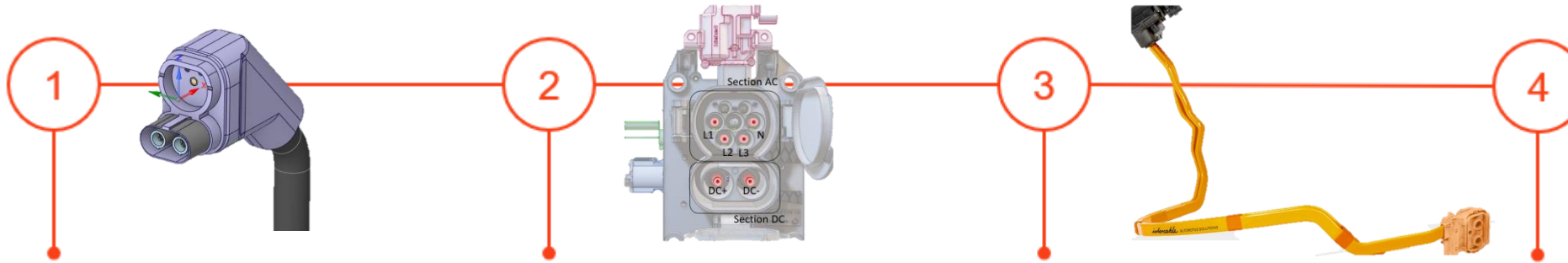
- Thermal and electrical conduction
- Natural or forced convection
- Thermal radiation
- Active cooling
- Unsteady behavior



**From the first concept  
to the validation**

# Factors influencing thermal behavior

- Ambient temperature
- Electric current load profile



## Charging Station

- Contact resistance
- Cable cross-section and length
- Insulation thermal conductivity
- Interface between conductor and coolant
- Direct/Indirect cooling
- Initial coolant temperature and flow rate
- Cooling unit

## Charging Inlet

- Contact resistance
- Cross-section of pin (CCS, NACS, GB/T, CHAdeMO, ChaoJi, Megawat)
- Busbar cross-section
- Thermal monitoring system efficiency

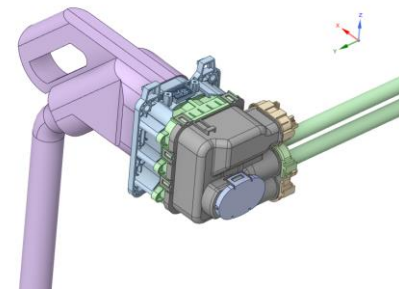
## Charging Harness

- Contact resistance
- Cable or busbar cross-section and material
- Insulation thermal conductivity
- Busbar orientation in space
- Passive cooling (or active cooling options)
- Separation between DC+/DC- line

## Battery Distribution Unit / Battery connection

- Contact resistance
- High-voltage components heat generation
- Internal busbars cross-sections

# Temperature limits



## Charging Coupler

- **50 K** temperature rise defined by the IEC standard
- Stress relaxation in mechanically working elastic copper alloys at elevated temperature (**any elevated temperature**)

## Charging Inlet

- **50 K** temperature rise defined by the IEC standard
- **150-175°C** silver plating limit depending on passivation
- **60°C** for metallic parts and **85°C** for non-metallic parts

## Charging Harness

- Insulation class, example: C class (3)  
**125°C** for 3000 h  
**150°C** for 240 h  
**175°C** for 6 h

## Battery Distribution Unit / Battery connection

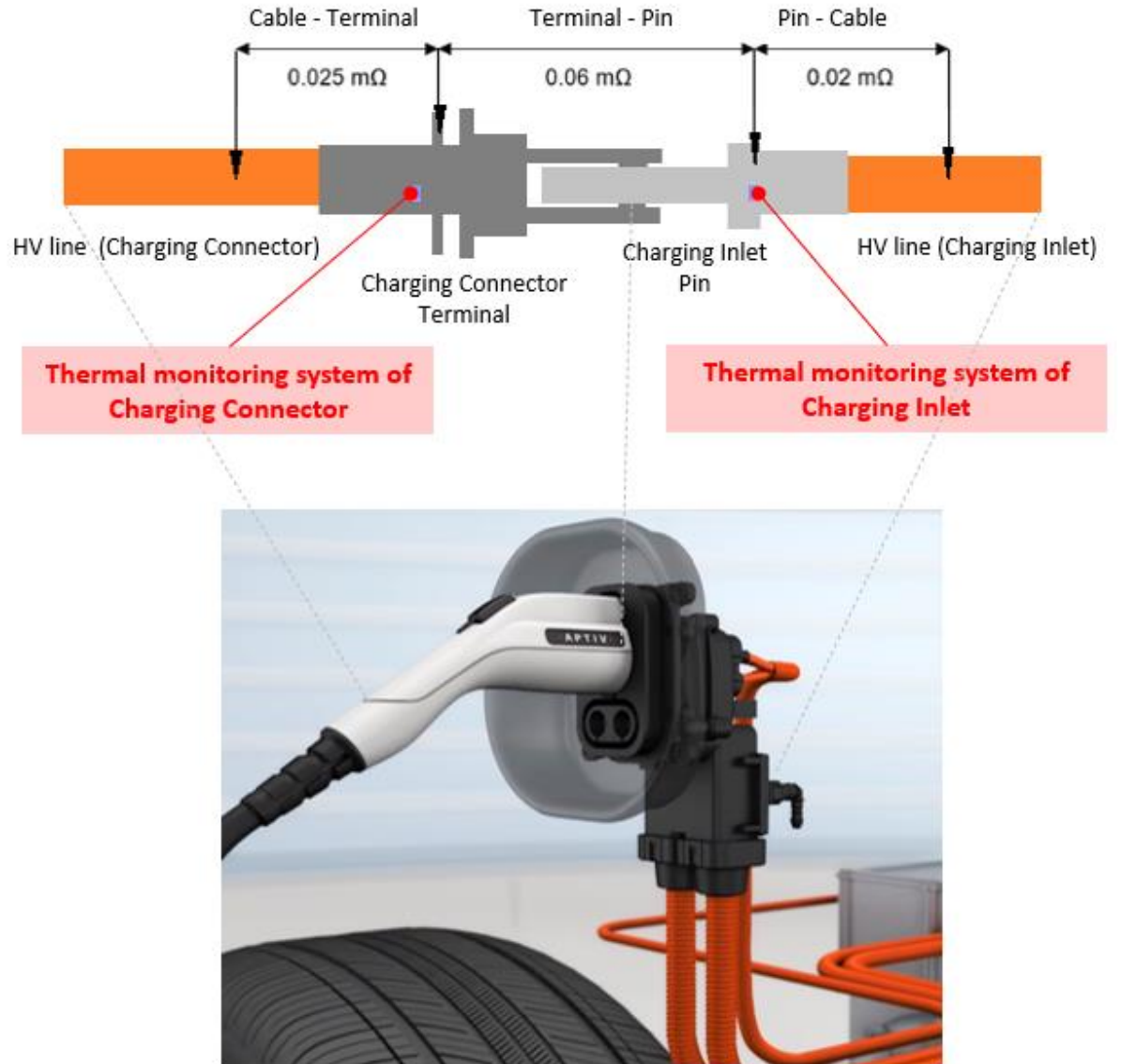
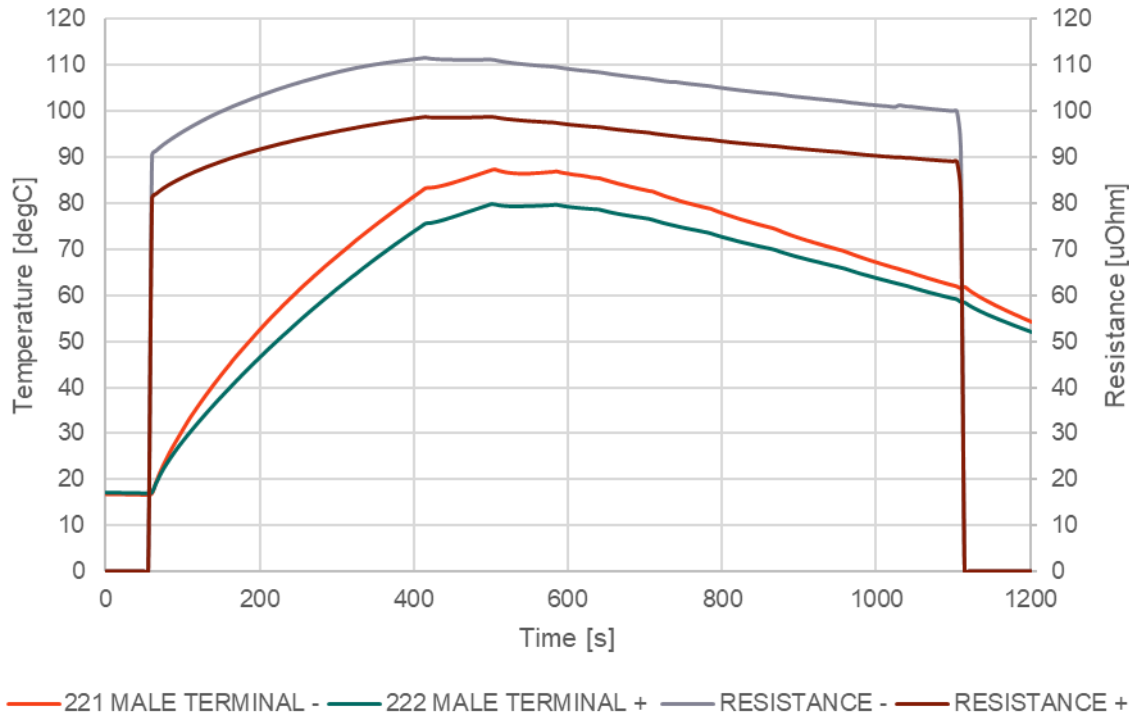
- **150-175°C** silver plating limit depending on passivation



# Contact resistance

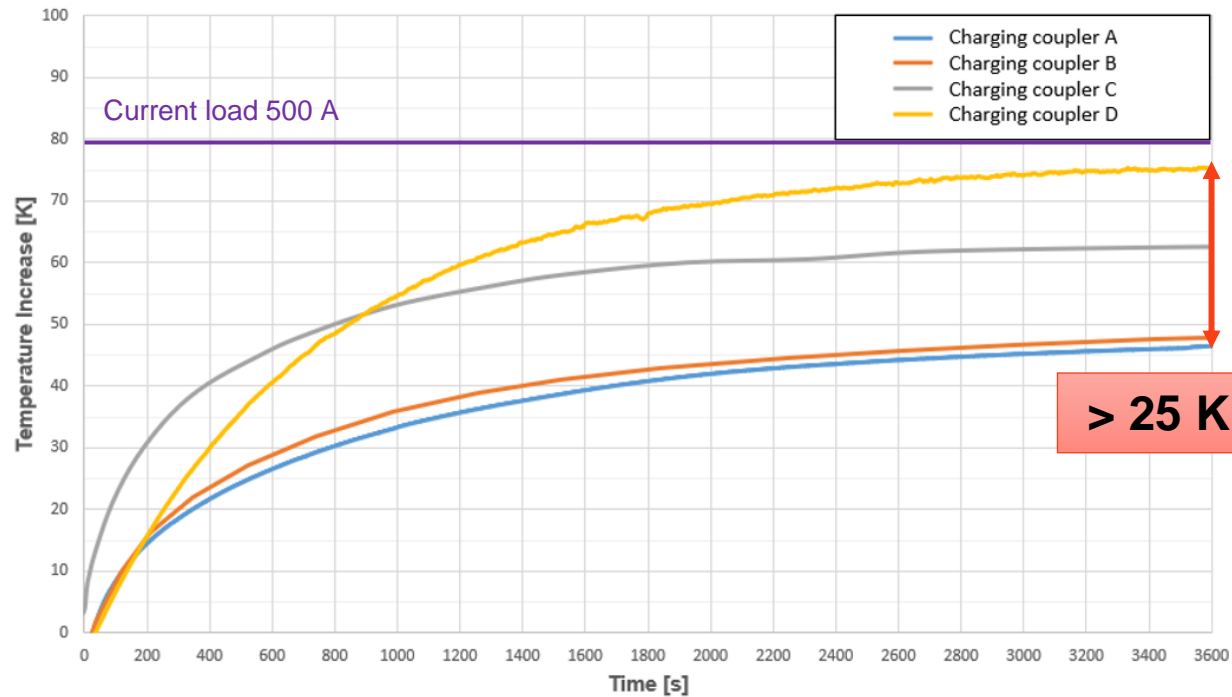
Very high influence on the results

- Every 10  $\mu\Omega$  can cause 10 K temperature rise!
- Pin cross-section is a bottleneck

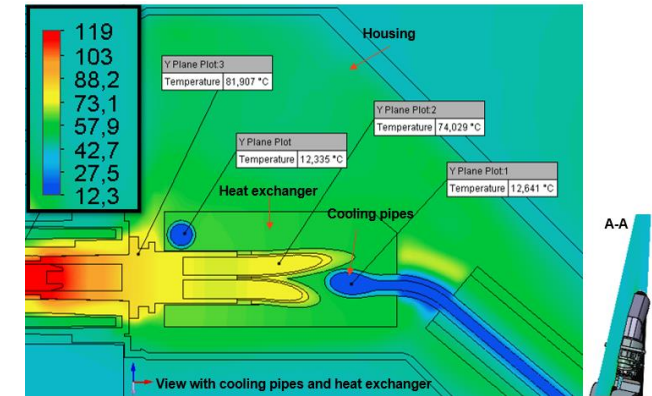


# Charging coupler

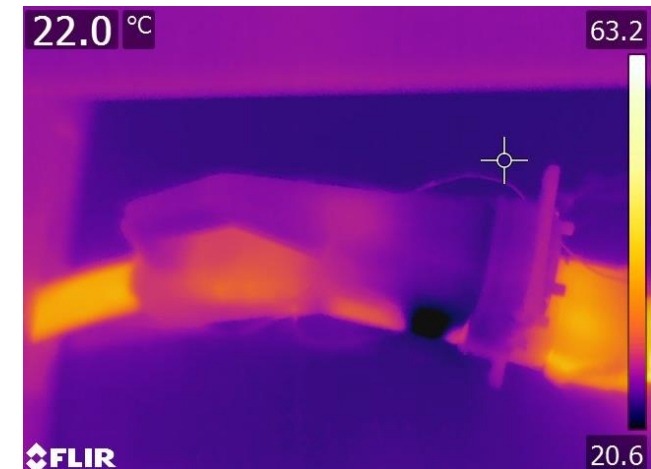
- Charging coupler type - very high influence on the temperature
- Comparison of charging couplers with the same rating:



Cross section with example temperature contour

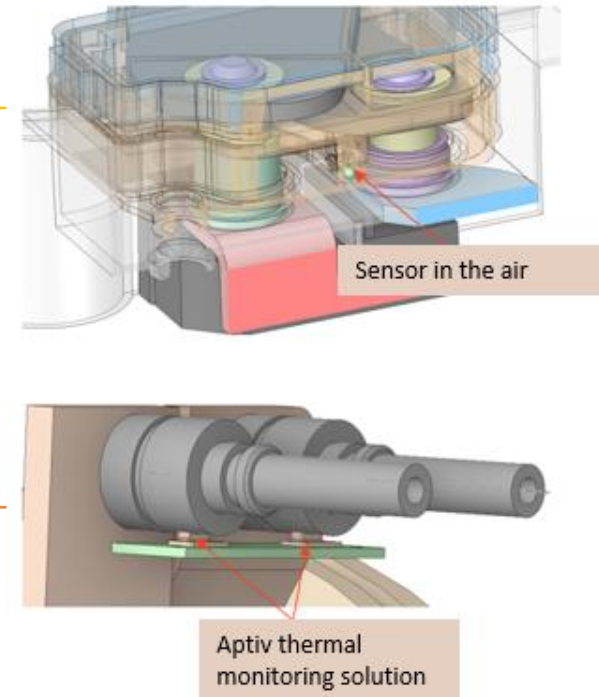
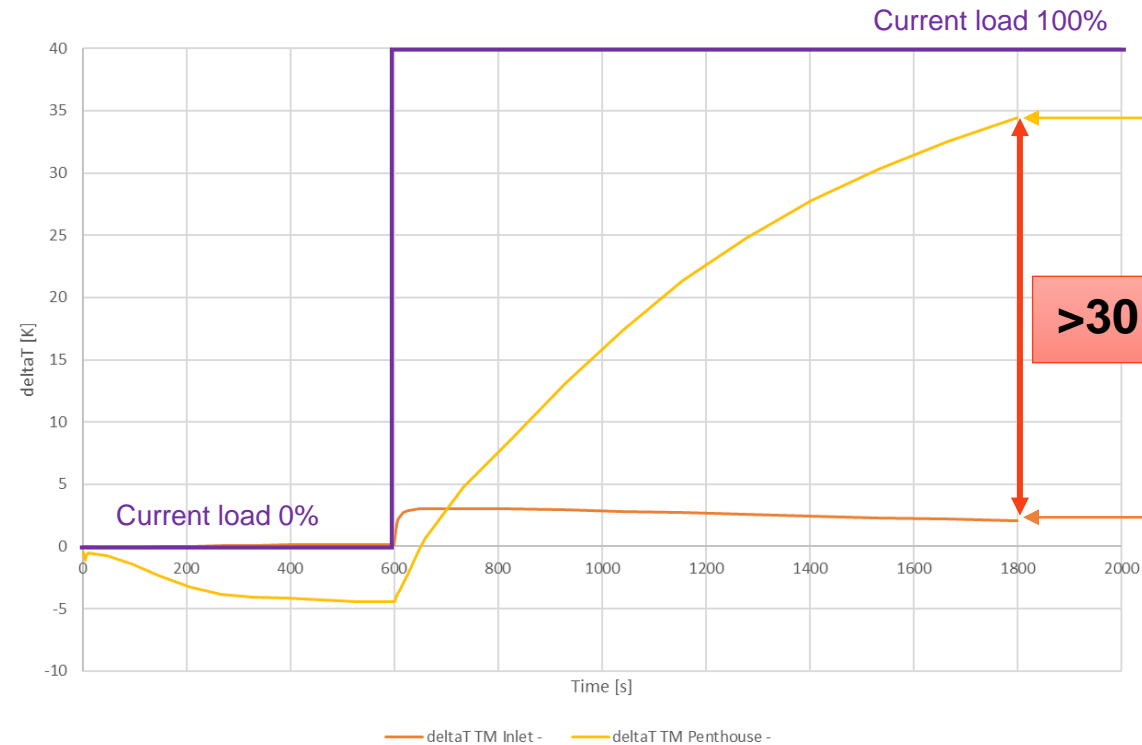


Real measurements using IR camera



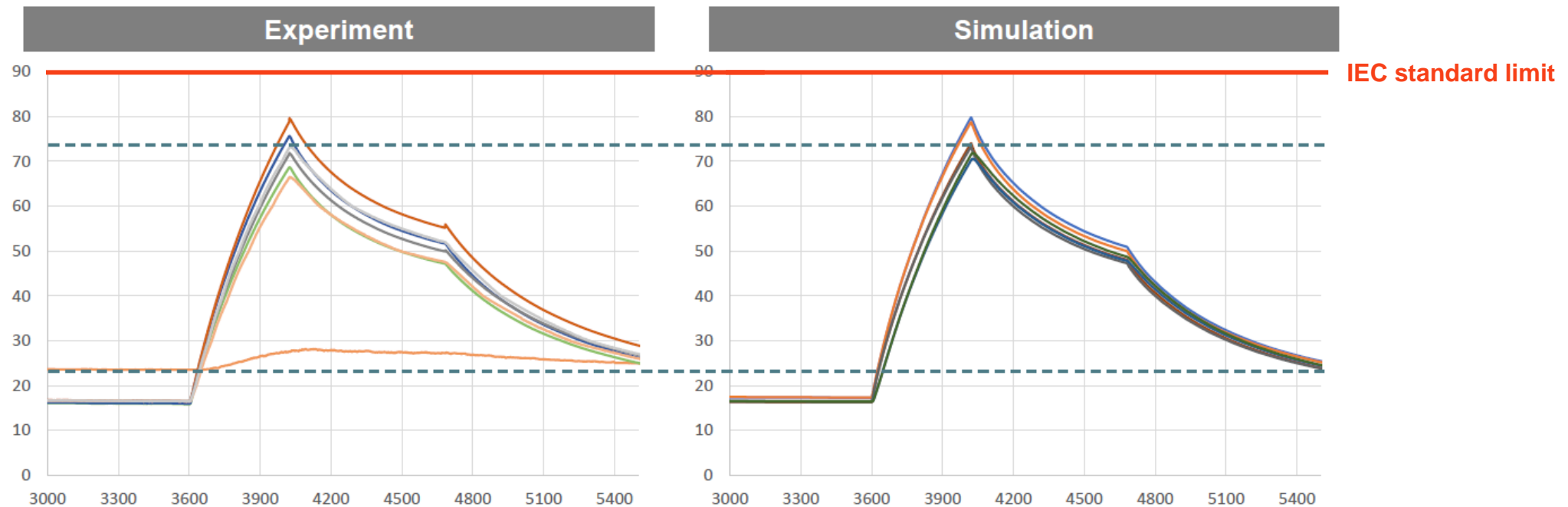
# Thermal monitoring system

- Thermal monitoring is responsible for switching off the charging if the permissible temperature is exceeded
- High-accuracy thermal monitoring system – cost reduction



# Experimental results

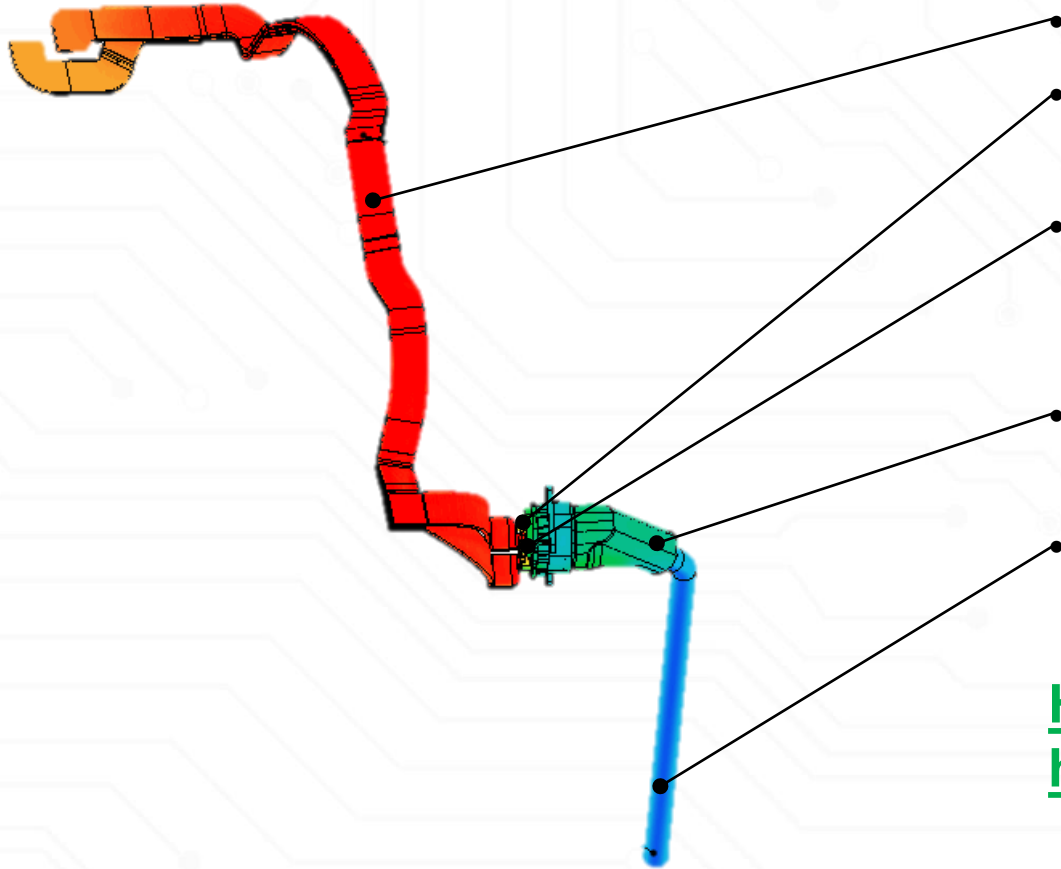
- Very good accuracy provided that the assumptions are made correctly
- Cooperation between: simulation team, product engineering, OEMs, and charging station manufacturers is very important





# Conclusions

## Weak points and solutions



**Inlet harness** → innovative active cooling solutions

**Inlet pin** → female terminal improvement, compensation by the harness and charging couplers

**Thermal monitoring accuracy** → the use of high-accuracy thermal monitoring systems prevents false shutdowns

**Charging Station** → good knowledge about charging coupler allows for better vehicle architecture design

**Cable and terminals cooling** → direct cooling

**High-fidelity thermal-electric-flow simulations help at every stage of the design!**

**Thank you.**